

## 150V P-Channel MOSFETs

### General Description

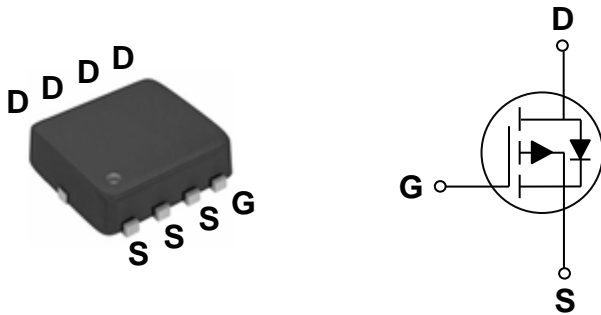
These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BVDSS	R <sub>DS(ON)</sub>	ID
-150V	780mΩ	-2A

### Features

- -150V,-2A, R<sub>DS(ON)</sub> =780mΩ @V<sub>GS</sub> = -10V
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

### PPAK3X3 Pin Configuration



### Applications

- Networking
- Load Switch
- LED applications

### Absolute Maximum Ratings

T<sub>c</sub>=25 °C unless otherwise noted

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	-150	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub>	Drain Current – Continuous (T <sub>c</sub> =25 °C)	-2	A
	Drain Current – Continuous (T <sub>c</sub> =100 °C)	-1.3	A
I <sub>DM</sub>	Drain Current – Pulsed <sup>1</sup>	-8	A
EAS	Single Pulse Avalanche Energy <sup>2</sup>	11.5	mJ
IAS	Single Pulse Avalanche Current <sup>2</sup>	4.8	A
P <sub>D</sub>	Power Dissipation (T <sub>c</sub> =25 °C)	7.8	W
	Power Dissipation – Derate above 25 °C	0.06	W/°C
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction to ambient	---	62	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction to Case	---	16	°C/W



# FTK02P15Z

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Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

### Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =-250uA	-150	---	---	V
ΔBV <sub>DSS</sub> /ΔT <sub>J</sub>	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25 °C, I <sub>D</sub> =1mA	---	0.12	---	V/°C
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =-150V, V <sub>GS</sub> =0V, T <sub>J</sub> =25 °C	---	---	-1	uA
		V <sub>DS</sub> =-120V, V <sub>GS</sub> =0V, T <sub>J</sub> =125 °C	---	---	-10	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	---	---	±100	nA

### On Characteristics

R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =-10V, I <sub>D</sub> =-1A	---	650	780	mΩ
		V <sub>GS</sub> =-6V, I <sub>D</sub> =-0.5A	---	700	950	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =-250uA	-2	-3	-4	V
ΔV <sub>GS(th)</sub>	V <sub>GS(th)</sub> Temperature Coefficient		---	-5.81	---	mV/°C
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =-10V, I <sub>D</sub> =-1A	---	2	---	S

### Dynamic and switching Characteristics

Q <sub>g</sub>	Total Gate Charge <sup>3, 4</sup>	V <sub>DS</sub> =-75V, V <sub>GS</sub> =10V, I <sub>D</sub> =-1A	---	4.4	8	nC	
Q <sub>gs</sub>	Gate-Source Charge <sup>3, 4</sup>		---	0.7	2		
Q <sub>gd</sub>	Gate-Drain Charge <sup>3, 4</sup>		---	1.5	3		
T <sub>d(on)</sub>	Turn-On Delay Time <sup>3, 4</sup>	V <sub>DD</sub> =-75V, V <sub>GS</sub> =-10V, R <sub>G</sub> =10Ω	---	12.5	20	ns	
T <sub>r</sub>	Rise Time <sup>3, 4</sup>		I <sub>D</sub> =-1A	---	8.9		18
T <sub>d(off)</sub>	Turn-Off Delay Time <sup>3, 4</sup>		---	---	17.3		36
T <sub>f</sub>	Fall Time <sup>3, 4</sup>		---	---	11.5		24
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =-75V, V <sub>GS</sub> =0V, F=1MHz	---	403	810	pF	
C <sub>oss</sub>	Output Capacitance		---	31	65		
C <sub>rss</sub>	Reverse Transfer Capacitance		---	18	40		
R <sub>g</sub>	Gate resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, F=1MHz	---	30	60	Ω	

### Drain -Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>S</sub>	Continuous Source Current	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	---	---	-2	A
I <sub>SM</sub>	Pulsed Source Current		---	---	-4	A
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> =-1A, T <sub>J</sub> =25 °C	---	---	-1	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> =0V, I <sub>S</sub> =1A, di/dt=100A/μs	---	70	---	ns
Q <sub>rr</sub>	Reverse Recovery Charge		T <sub>J</sub> =25 °C	---	114	---

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. V<sub>DD</sub>=50V, V<sub>GS</sub>=10V, L=1mH, I<sub>AS</sub>=4.8A., R<sub>G</sub>=25Ω, Starting T<sub>J</sub>=25 °C.
3. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%.
4. Essentially independent of operating temperature.



# FTK02P15Z

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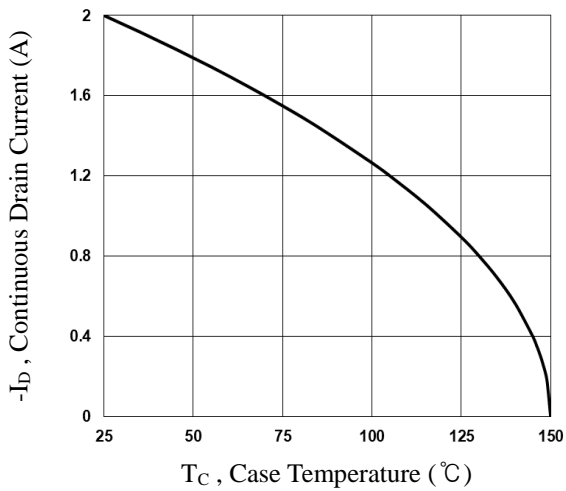


Fig.1 Continuous Drain Current vs.  $T_C$

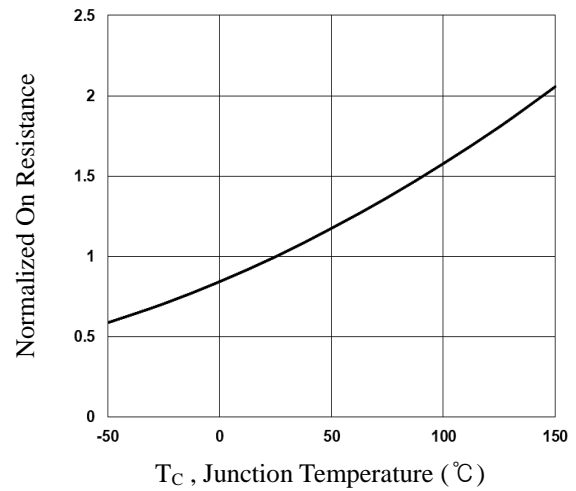


Fig.2 Continuous Drain Current vs.  $T_C$

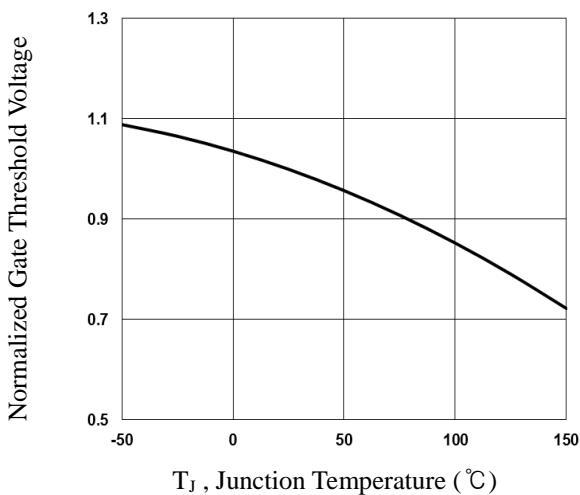


Fig. 3 Normalized  $V_{th}$  vs.  $T_J$

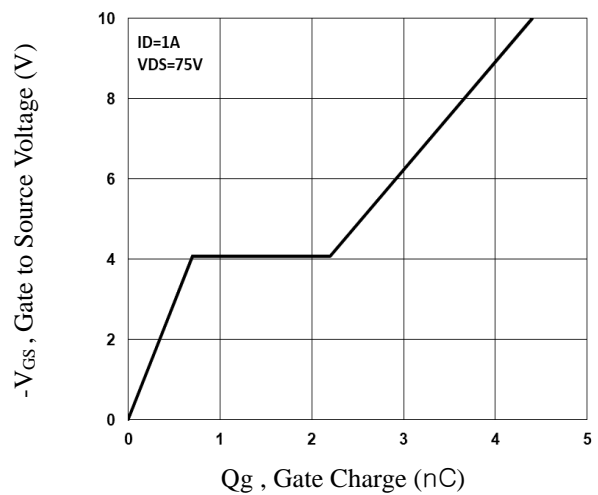


Fig. 4 Gate Charge Waveform

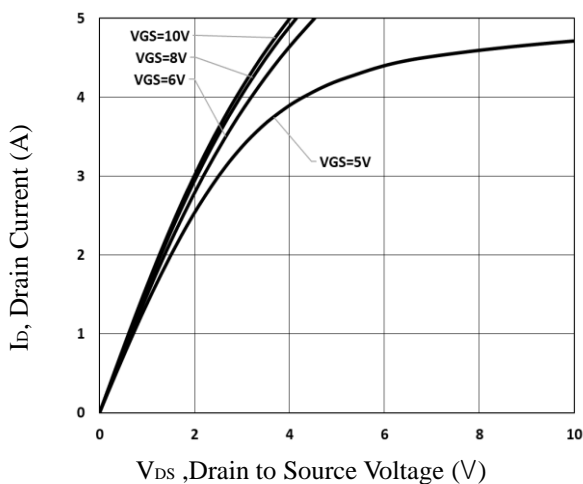


Fig. 5 Typical Output Characteristics

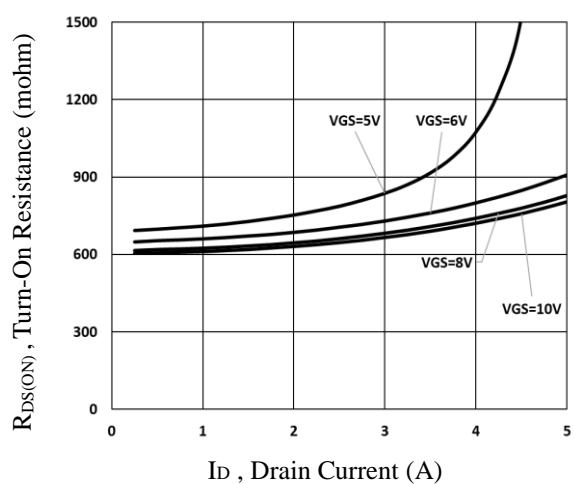
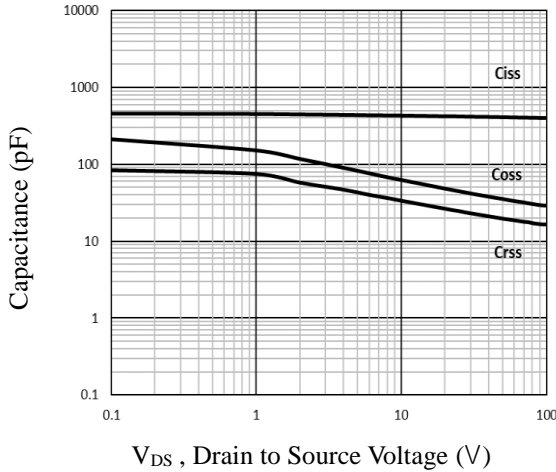


Fig. 6 Turn - On Resistance vs.  $I_D$

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$V_{DS}$ , Drain to Source Voltage (V)  
Fig. 7 Capacitance Characteristics

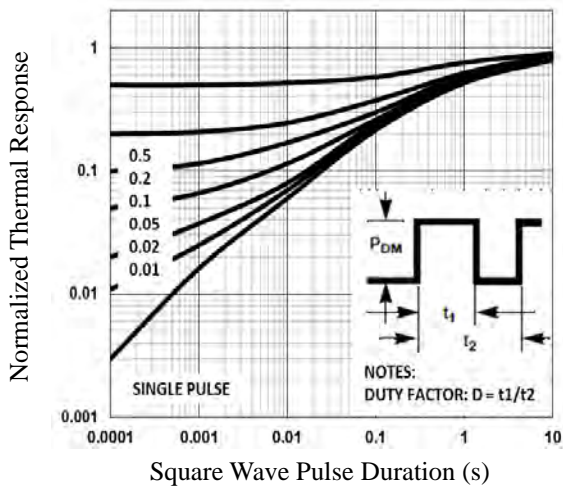


Fig. 8 Normalized Transient Impedance

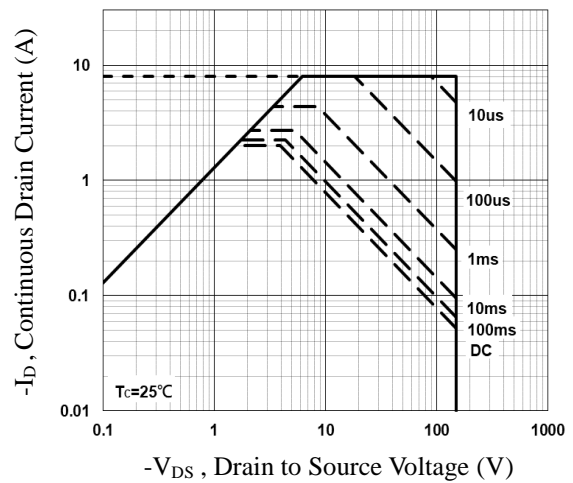


Fig. 9 Maximum Safe Operation Area

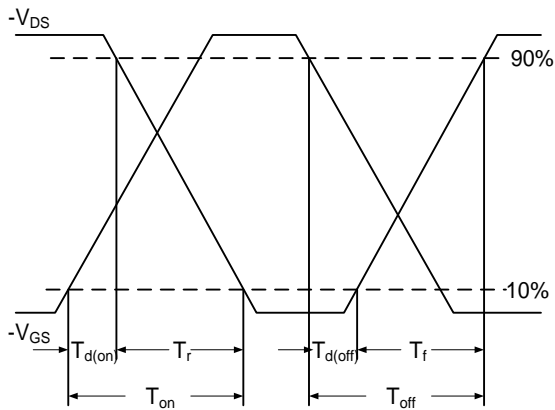


Fig. 10 Switching Time Waveform

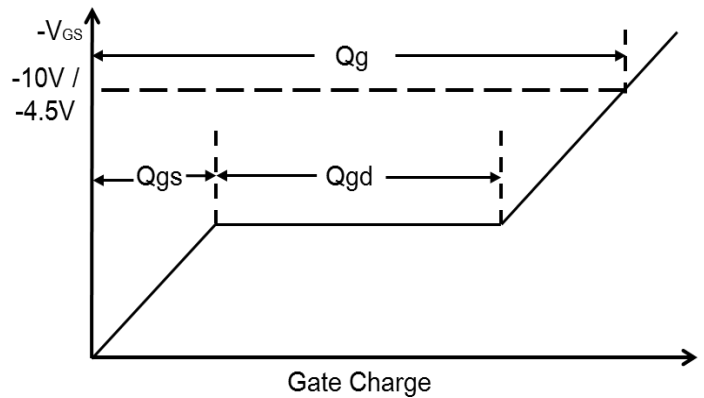
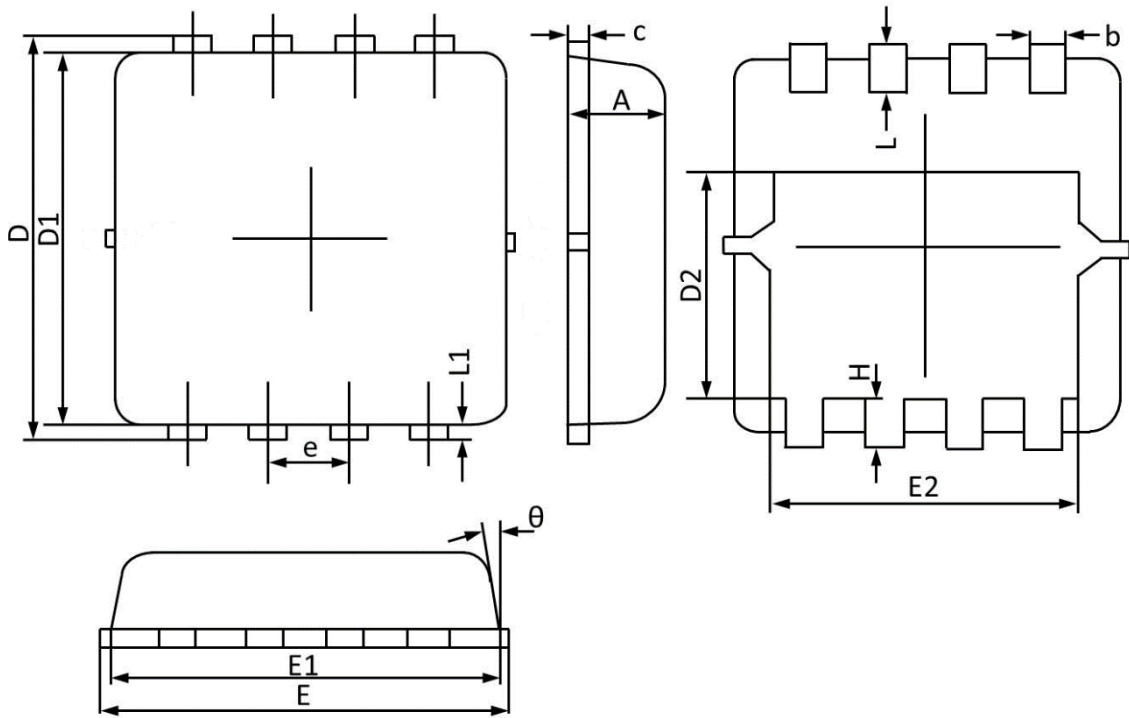


Fig. 11 Gate Charge Waveform

## 150V P-Channel MOSFETs

### PPAK3x3 PACKAGE INFORMATION



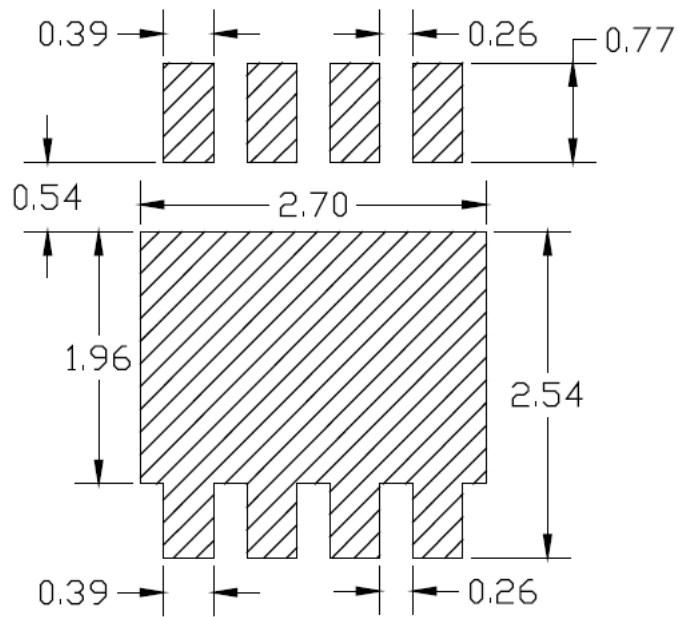
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	0.900	0.700	0.035	0.028
b	0.350	0.250	0.014	0.010
c	0.250	0.100	0.010	0.004
D	3.500	3.050	0.138	0.120
D1	3.200	2.900	0.126	0.114
D2	1.950	1.350	0.077	0.053
E	3.400	3.000	0.134	0.118
E1	3.300	2.900	0.130	0.114
E2	2.600	2.350	0.102	0.093
e	0.65BSC		0.026BSC	
H	0.750	0.300	0.030	0.012
L	0.600	0.300	0.024	0.012
L1	0.200	0.060	0.008	0.002
θ	14°	6°	14°	6°



# FTK02P15Z

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### RECOMMENDED LAND PATTERN



unit : mm